

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A polyamide molding compound having comprising

~~(1)~~ a partially crystalline polyamide, which includes a partially aromatic copolyamide, and ~~(2)~~ a mineral filler,

characterized in that the mineral filler, ~~before it is added to the polyamide, consists essentially of~~ is uncoated precipitated ultrafine chalk (CaCO_3) ~~provided as precipitated ultrafine chalk having an average particle size of at most 100 nm, the molding compound being substantially free of any other filler.~~

2. (Previously Presented) The polyamide molding compound according to Claim 1,

characterized in that it includes at most 40 weight-percent of said ultrafine chalk.

3. (Previously Presented) The polyamide molding compound according to Claim 1,

characterized in that the ultrafine chalk has an average particle size of at most 90 nm.

4. (Previously Presented) The polyamide molding compound according to Claim 1,

characterized in that the partially aromatic copolyamide is based on the monomers hexamethylene diamine and aromatic dicarboxylic acids.

5. (Original) The polyamide molding compound according to Claim 4,

characterized in that the aromatic dicarboxylic acids include terephthalic acid and isophthalic acid in the ratio 70/30.

6. (Previously Presented) A blank made of an injection-molded polyamide molding compound according to Claim 1,

characterized in that it includes a smooth surface having a high gloss, produced by a molding tool polished to a high gloss.

7. (Original) A reflector for vehicle driving illuminators, turn signals, or street lamps, and/or a sub-reflector for vehicle driving illuminators

characterized in that it includes a blank according to Claim 6 and is metalized directly.

8. (Previously Presented) The reflector or sub-reflector according to Claim 7,

characterized in that the metal coating is a PVD layer having an iridescence temperature at a value which is higher than 220°C.

Claims 9-12. (Cancelled)

13. (Previously Presented) The polyamide molding compound of Claim 3,

wherein said average particle size is at most 80 nm.

14. (Previously Presented) The polyamide molding compound according to Claim 2,

characterized in that the ultrafine chalk has an average particle size of at most 70 nm.

15. (Currently Amended) A polyamide molding compound having comprising

a partially crystalline polyamide, which includes a partially aromatic copolyamide, and a mineral filler admixed therewith,

characterized in that the mineral filler ~~when fed to the polyamide is as~~ uncoated ultrafine chalk (CaCO_3) having an average particle size of at most 80 nm, ~~and~~

~~wherein the molding compound is substantially free of any other filler.~~

16. (Previously Presented) The polyamide molding compound of claim 15 wherein the ultrafine chalk has an average particle size of at most 70nm.

Claims 17 and 18. (Cancelled)